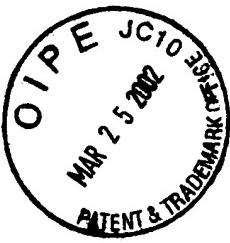


JC05 Rec'd PCT/PTO 25 MAR 2002 #7  
Pct 14  
4-09-02



ATTY. DKT. NO. P67440US0

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Johshi GOTOH et al.

Serial No.: 10/019,299

Filed: January 7, 2002

For: UNDERFILLING MATERIAL FOR SEMICONDUCTOR PACKAGE

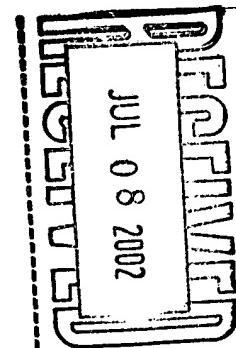
INFORMATION DISCLOSURE STATEMENT

Commissioner of Patents  
Washington, DC 20231

Sir:

As a means of complying with the duty of disclosure under 37 CFR §1.56, and in accordance with 37 CFR §§1.97 and 1.98, Applicant(s), through the undersigned attorney, submits this Information Disclosure Statement. The patents, publications or other information submitted herewith are listed on the attached Form PTO-1449 and copies are attached. Cited in the International Search Report (copy attached) are WO 98/31738 A, EP O 757 067A, US 5,061,776 , and "SOLDER JOINT LIFE IMPROVEMENT USING ADHESIVE UNDER COMPONENT" page 32. JP-10-204259-A is cited and discussed in the present specification.

In accordance with 37 CFR §1.97(b)(1) or (2), this Information Disclosure Statement is being filed either within three months of the filing date of the above-identified application.



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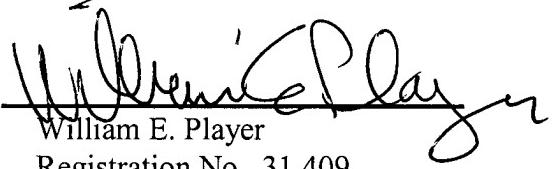
**U.S. Patent Application No.: 10/019,299  
Attorney Docket No.: P67440US0**

within three months of the date of entry into the national stage of the above-identified application as set forth in 37 CFR §1.491. Accordingly, no fee is required.

Respectfully submitted,

JACOBSON HOLMAN PLLC

By:

  
William E. Player  
Registration No. 31,409

**Dated: March 25, 2002**

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WEP/rdt

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Sheet 1 of 1

FORM PTS 1449 (modified)

ATTY DOCKET NO.:

SERIAL NO.:

P67440US0

10/019,299

APPLICANT: Johshi GOTOH et al.

FILING DATE: January 7, 2002

GROUP: Unassigned

Date Entered PTO: March 25, 2002

## U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	5,061,776	10/1991	WEAVER et al.			

## FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES	TRANSLATION NO
	JP2713760-B	09/1990	JAPAN (English Abstract)				
	JP2738487-B	06/1994	JAPAN (English Abstract)				
	JP10204259-A	08/1998	JAPAN (English Abstract)				
	WO 98/31738	01/1998	PCT				
	EP 0757067A1	03/1995	EUROPEAN				

## OTHER DOCUMENT(S) (Including Author, Title, Date, Pertinent Pages, Etc.)

"Solder Joint Life Improvement Using Adhesive Under Component", Research Disclosure - 2244 - (January, 1990)  
No. 309, New York, US - XP 000099320

EXAMINER

DATE CONSIDERED